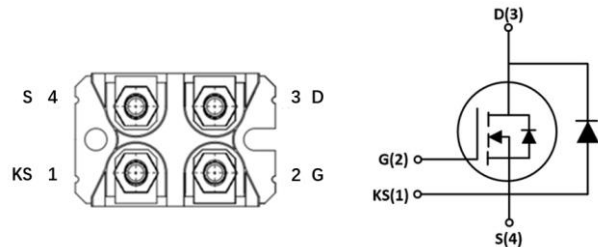


IVST12017MA1L – 1200V 17mΩ MOSFET + 40A SBD SiC Module

Features

- High blocking voltage with low on-resistance
- High speed switching with low capacitance
- High operating junction temperature capability
- Integrated silicon carbide diode
- Kelvin gate input easing driver circuit design
- Freewheeling diode with zero reverse recovery

Package



Applications

- Introduction heating and welding
- Battery charger
- Photovoltaic inverter
- High frequency DC-DC converter

Part Number	Package
IVST12017MA1L	SOT 227

Absolute Maximum Ratings (T_c=25°C unless otherwise specified)

Symbol	Parameter	Value	Unit	Test Conditions	Note
SiC MOSFET					
V _{DS}	Drain-Source voltage	1200	V	V _{GS} =0V, I _D =100μA	
V _{GSmax} (DC)	Maximum DC voltage	-5 to 22	V	Static (DC)	
V _{GSmax} (Spike)	Maximum spike voltage	-10 to 25	V	<1% duty cycle, and pulse width<200ns	
V _{GSon}	Recommended turn-on voltage	20±0.5	V		
V _{GSoff}	Recommended turn-off voltage	-3.5 to -2	V		
I _D	Drain current (continuous)	121	A	V _{GS} =20V, T _c =25°C	Fig. 21
		85	A	V _{GS} =20V, T _c =100°C	
I _{DM}	Drain current (pulsed)	302	A	Pulse width limited by SOA	Fig. 24
P _{TOT}	Total power dissipation	464	W	T _c =25°C	Fig. 22
T _{stg}	Storage temperature range	-55 to 175	°C		
T _J	Operating junction temperature	-55 to 175	°C		
SiC SBD					
V _{RRM}	Reverse voltage (repetitive peak)	1200	V		
V _{DC}	DC blocking voltage	1200	V		
I _F	Forward current (continuous)	86	A	T _c =25°C	
		40	A	T _c =136°C	
I _{FSM}	Surge non-repetitive forward current	260	A	sine halfwave @T _c =25°C tp=10ms	
I _{FRM}	Surge repetitive forward current	220	A	sine halfwave @T _{amb} =25°	

				C tp=10ms, Freq=0.1Hz, 100cycles	
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Electrical Characteristics (T_c=25°C unless otherwise specified)

Symbol	Parameter	Value			Unit	Test Conditions	Note
		Min.	Typ.	Max.			
I _{DSS}	Zero gate voltage drain current		5	100	μA	V _{DS} =1200V, V _{GS} =0V	
I _{GSS}	Gate leakage current			±100	nA	V _{DS} =0V, V _{GS} =-5~20V	
V _{TH}	Gate threshold voltage	1.8	3.2	5	V	V _{GS} =V _{DS} , I _D =18mA	Fig. 8, 9
			2.4			V _{GS} =V _{DS} , I _D =18mA @ T _C =175°C	
R _{ON}	Static drain-source on-resistance		17	21	mΩ	V _{GS} =20V, I _D =60A @T _J =25°C	Fig. 4, 5, 6, 7
			31.4		mΩ	V _{GS} =20V, I _D =60A @T _J =175°C	
C _{ISS}	Input capacitance		5730		pF	V _{DS} =800V, V _{GS} =0V, f=100kHz, V _{AC} =25mV	Fig. 16
C _{OSS}	Output capacitance		417		pF		
C _{RSS}	Reverse transfer capacitance		29.6		pF		
E _{OSS}	C _{OSS} stored energy		168		μJ		
Q _g	Total gate charge		280		nC	V _{DS} =800V, I _D =60A, V _{GS} =-5 to 20V	Fig. 18
Q _{gs}	Gate-source charge		96		nC		
Q _{gd}	Gate-drain charge		76		nC		
R _g	Gate input resistance		1.55		Ω	f=1MHz	
E _{ON}	Turn-on switching energy		1291		μJ	V _{DS} =800V, I _D =60A, V _{GS} =-3.6 to 20V, R _{G(ext)} =3.3Ω, L=200μH	Fig. 19, 20
E _{OFF}	Turn-off switching energy		743.8		μJ		
t _{d(on)}	Turn-on delay time		19.2		ns		
t _r	Rise time		45.6				
t _{d(off)}	Turn-off delay time		59.6				
t _f	Fall time		28.8				
SiC SBD							
V _F	Forward Voltage		1.48	1.80	V	I _F = 40 A T _J =25°C	Fig. 25
			2.30	3.00		I _F = 40 A T _J =175°C	
I _R	Reverse Current		10	300	μA	V _R = 1200 V T _J =25°C	Fig. 26
			60	1000		V _R = 1200 V T _J =175°C	
t _{rr}	Reverse recovery time		26.2		ns	V _{DS} =800V, di/dt=3050A/μs,	
Q _{rr}	Reverse recovery charge		430.1		nC	V _{GS} =-3.6 to 20V,	
I _{RRM}	Peak reverse recovery current		29.6		A	R _{G(ext)} =5.1Ω, L=200μH, T _J =25°C	

Reverse Diode Characteristics ($T_c=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Value			Unit	Test Conditions	Note
		Min.	Typ.	Max.			
V_{SD}	Diode forward voltage		3.5		V	$I_{SD}=30\text{A}, V_{GS}=0\text{V}$	Fig. 10, 11, 12
			3.2		V	$I_{SD}=30\text{A}, V_{GS}=0\text{V}, T_J=175^\circ\text{C}$	
t_{rr}	Reverse recovery time		22.8		ns	$V_{GS}=-3.5\text{V}/+20\text{V}, I_{SD}=60\text{A}, V_R=800\text{V}, R_{G(\text{ext})}=7.5\Omega, di/dt=3050\text{A}/\mu\text{s}, L=200\mu\text{H}$	
Q_{rr}	Reverse recovery charge		418		nC		
I_{RRM}	Peak reverse recovery current		31.6		A		

Thermal Data

Symbol	Parameter	Value	Unit	Note
$R_{\theta(J-C)}$	Thermal Resistance from Junction to Case	0.323	$^\circ\text{C}/\text{W}$	Per MOSFET Fig. 23
$R_{\theta(J-C)}$	Thermal Resistance from Junction to Case	0.427	$^\circ\text{C}/\text{W}$	Per SBD

Module Characteristics

Symbol	Parameter	Conditions	Value			Unit
			Min.	Typ.	Max.	
V_{ISOL}	Isolation voltage	RMS, $f=50/60\text{Hz}, t=10\text{sec}, I_{ISOL} \leq 1\text{mA} *$	3.0			kV
T_{STG}	Storage temperature		-40		150	$^\circ\text{C}$
M	Terminal connection torque	Screw M4	1.1		1.5	N·m
	Mounting torque	Screw M4	1.1		1.5	N·m
G	Weight of module			27		g
	Creepage distance	Terminal to heatsink		10.61		mm
		Terminal to terminal		10.37		mm
	Clearance distance	Terminal to heatsink		6.7		mm
		Terminal to terminal		4.05		mm

*: 1. Isolation voltages are between terminals and baseplate.

2. All terminals are connected together during the test.

Typical Performance (curves)

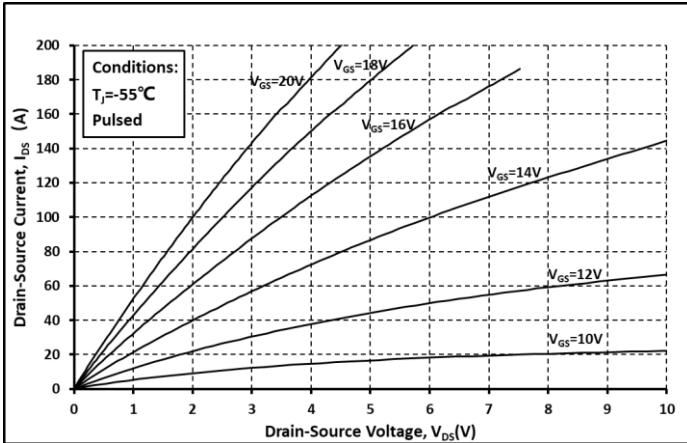


Fig. 1 Output Curve @ $T_j = -55^\circ\text{C}$

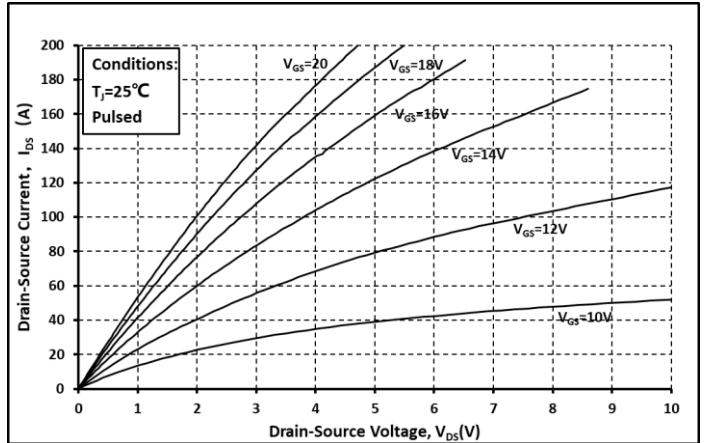


Fig. 2 Output Curve @ $T_j = 25^\circ\text{C}$

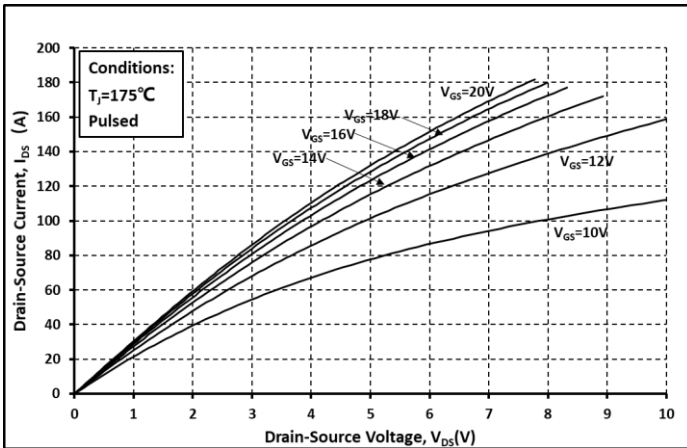


Fig. 3 Output Curve @ $T_j = 175^\circ\text{C}$

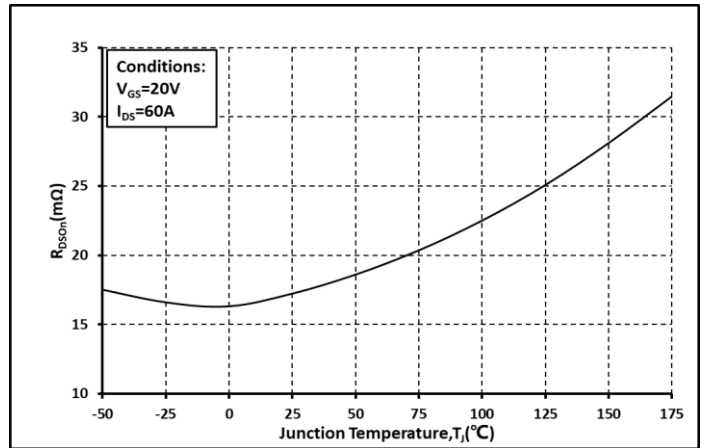


Fig. 4 R_{on} vs. Temperature

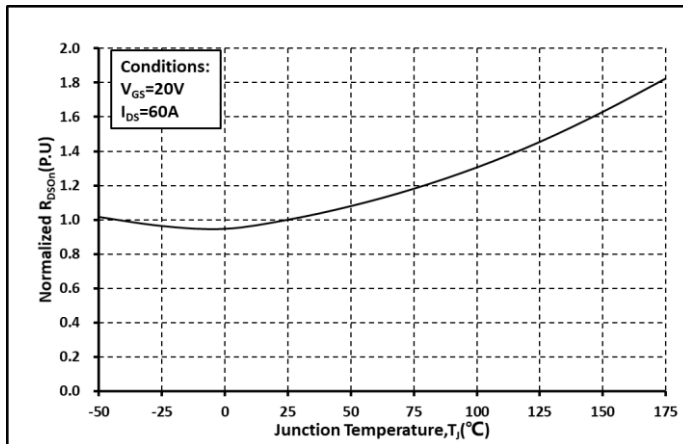


Fig. 5 Normalized R_{on} vs. Temperature

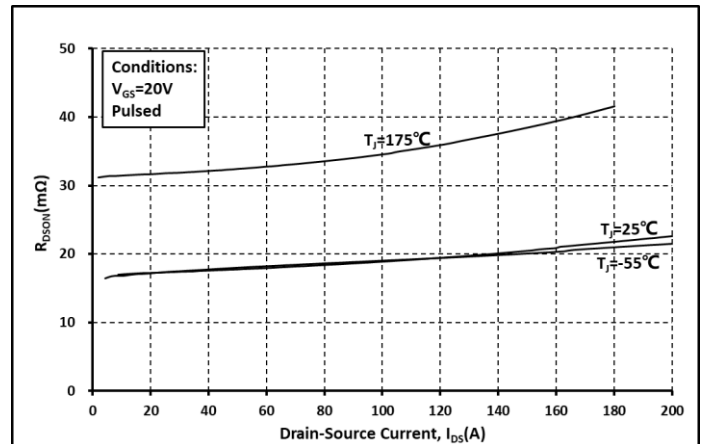


Fig. 6 R_{on} vs. I_{DS} @ Various Temperature

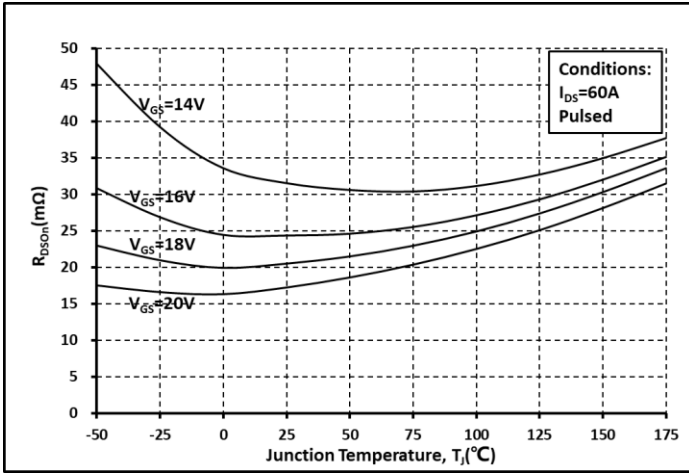


Fig. 7 Ron vs. Temperature @ Various V_{GS}

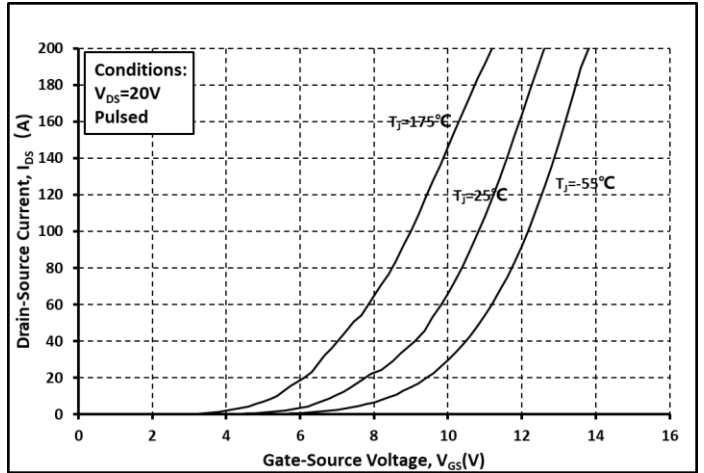


Fig. 8 Transfer Curves @ Various Temperature

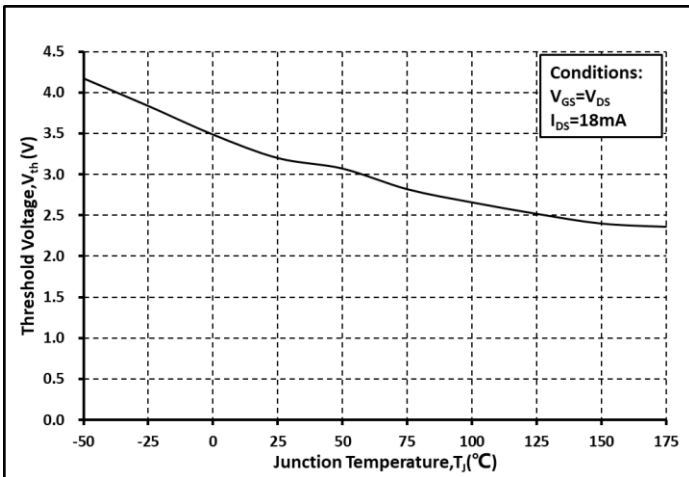


Fig. 9 Threshold Voltage vs. Temperature

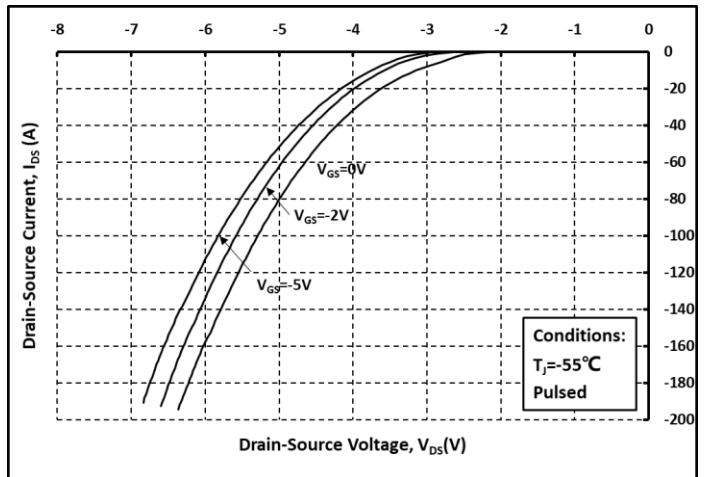


Fig. 10 Body Diode curves @ T_J =-55 $^{\circ}$ C

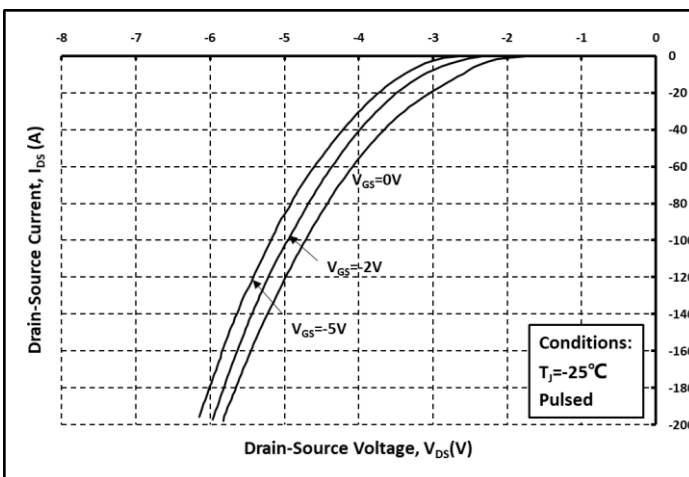


Fig. 11 Body Diode curves @ T_J =25 $^{\circ}$ C

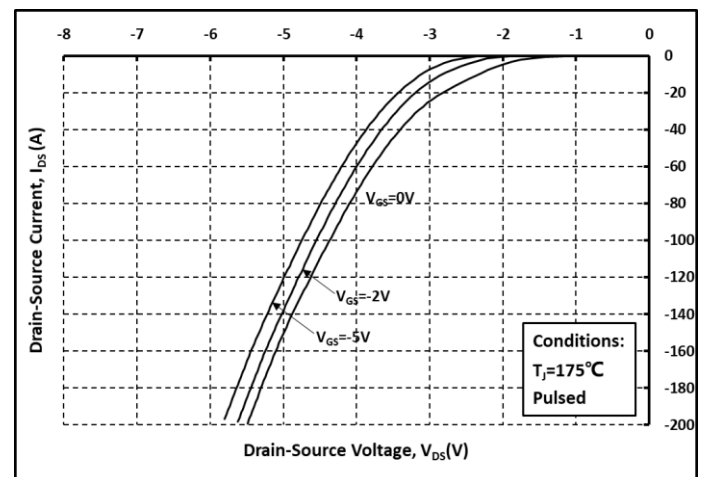


Fig. 12 Body Diode curves @ T_J =175 $^{\circ}$ C

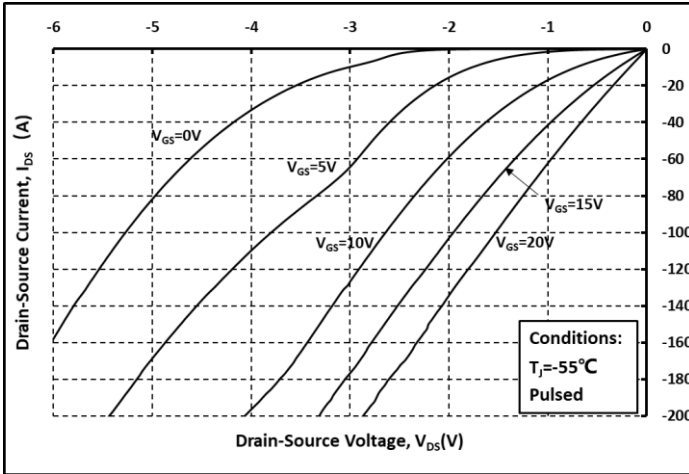


Fig. 13 3rd Quadrant curves @ $T_j = -55^\circ\text{C}$

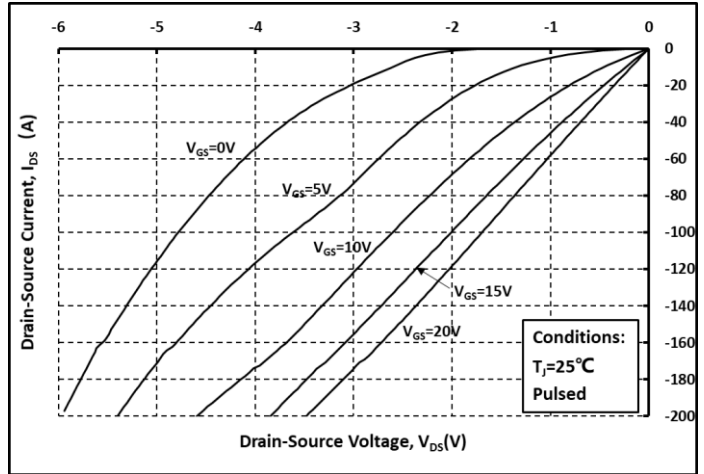


Fig. 14 3rd Quadrant curves @ $T_j = 25^\circ\text{C}$

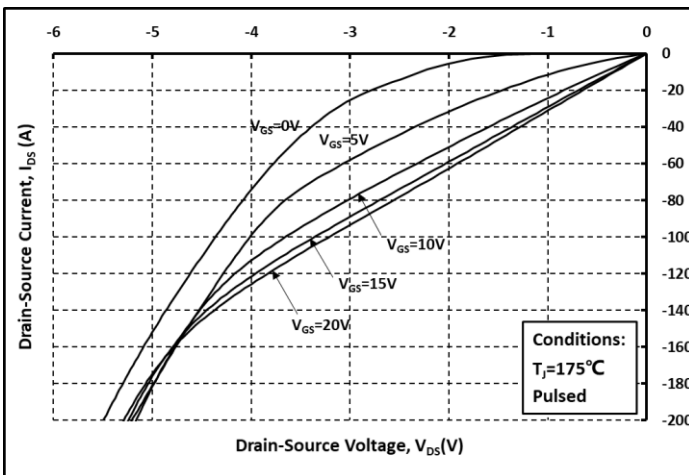


Fig. 15 3rd Quadrant curves @ $T_j = 175^\circ\text{C}$

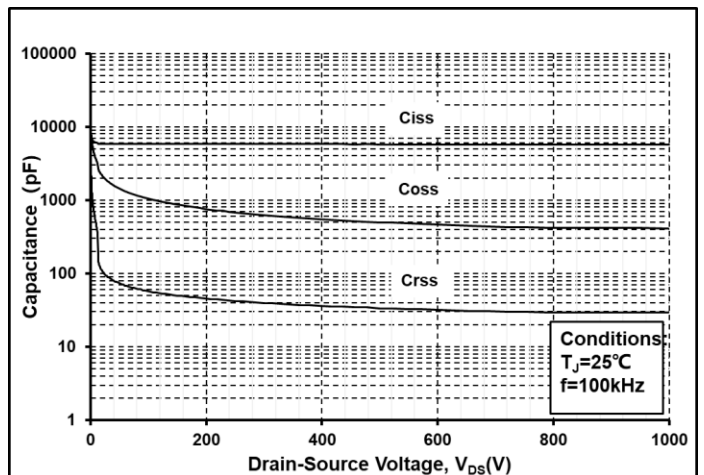


Fig. 16 Capacitance vs. V_{DS}

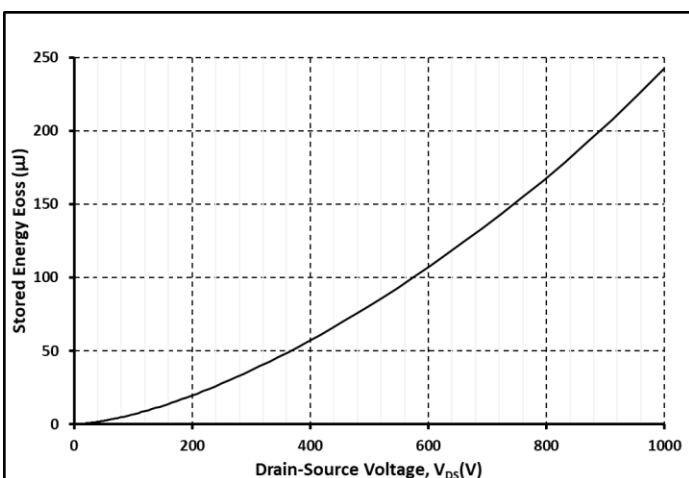


Fig. 17 Output Capacitor Stored Energy

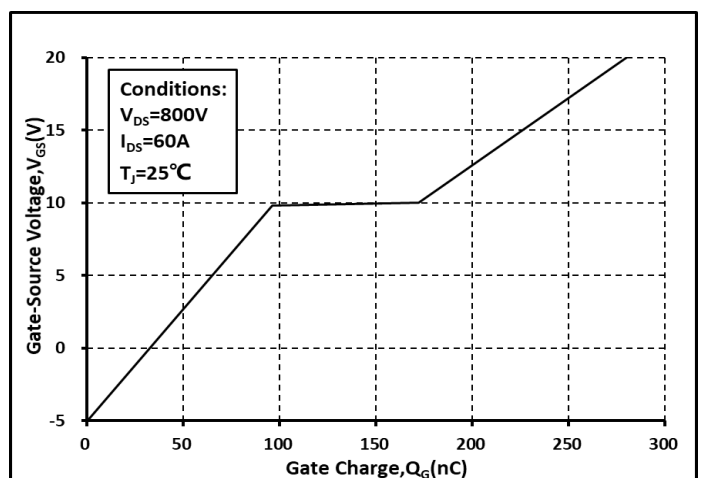


Fig. 18 Gate Charge Characteristics

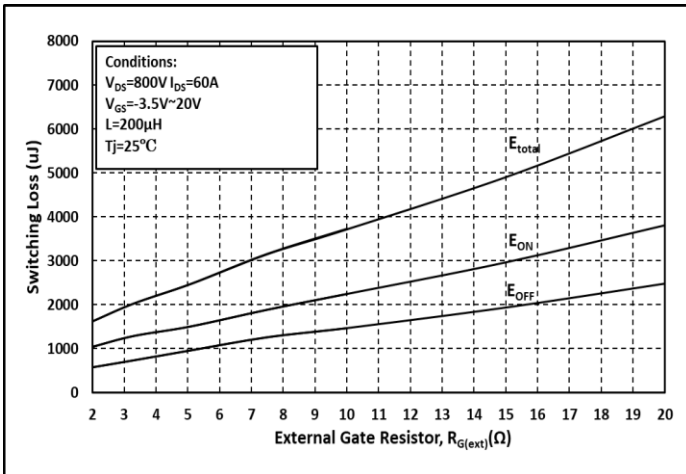


Fig. 19 Switching Energy vs. $R_{G(ext)}$

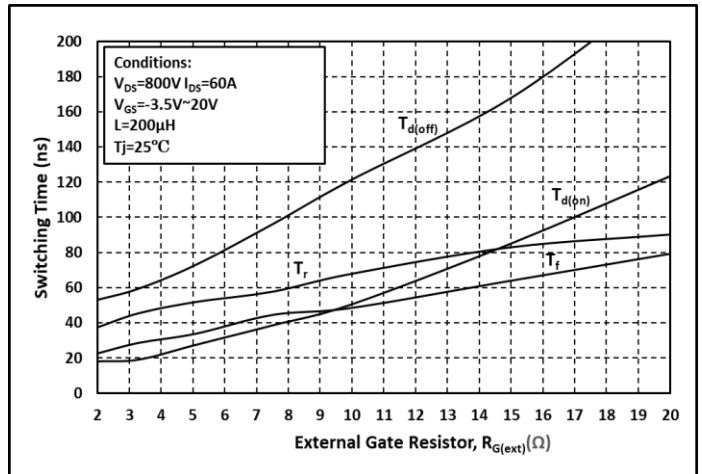


Fig. 20 Switching Times vs. $R_{G(ext)}$

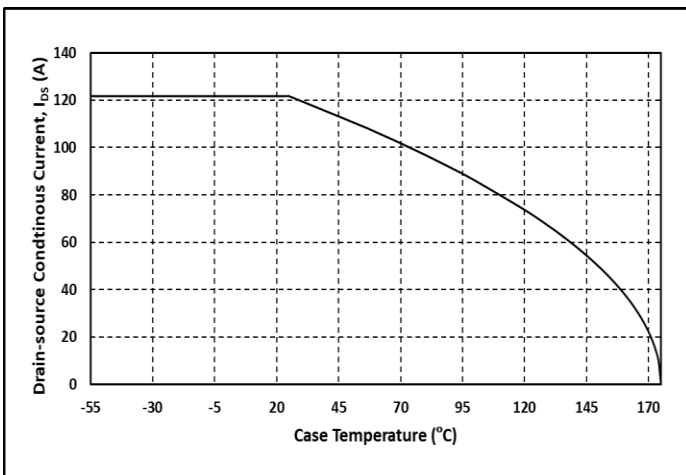


Fig. 21 Continuous Drain Current vs. Case Temperature

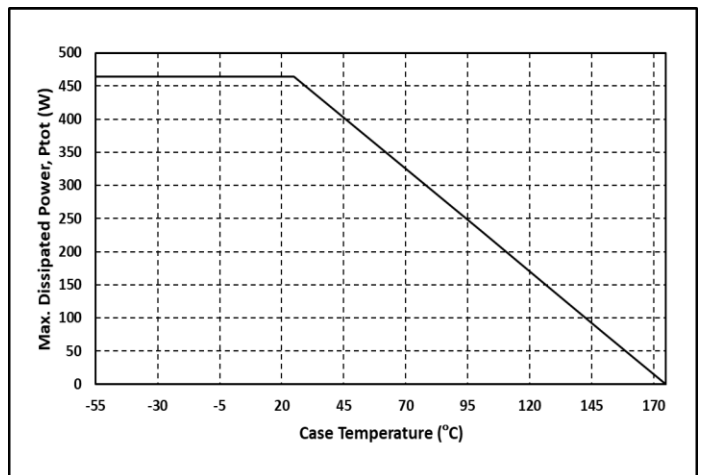


Fig. 22 Max. Power Dissipation Derating vs. Case Temperature

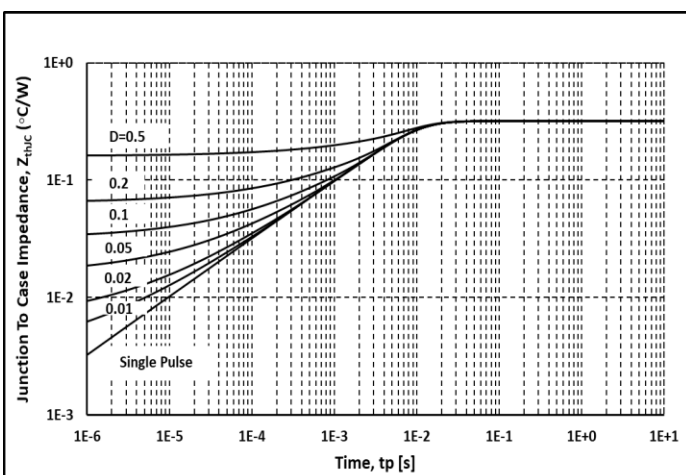


Fig. 23 Thermal impedance (MOSFET)

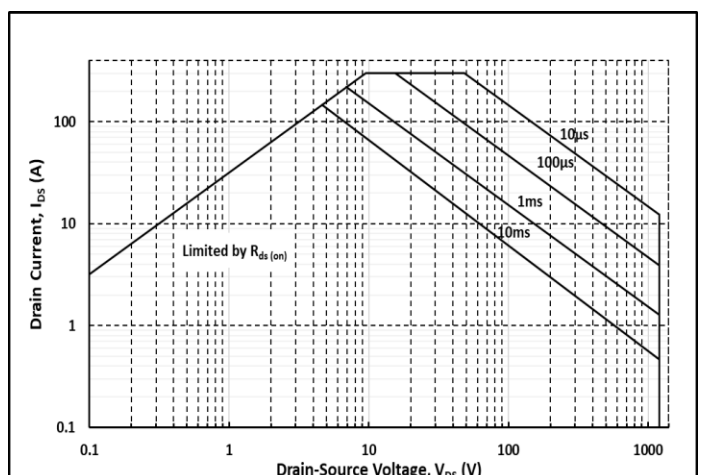


Fig. 24 Safe Operating Area

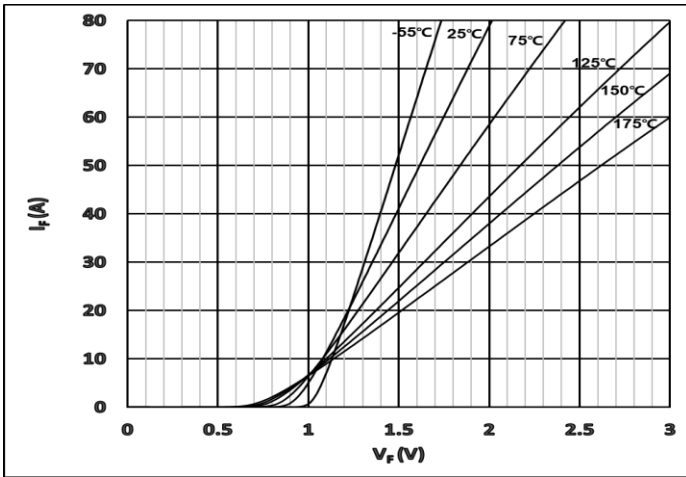


Fig. 25 Typical Forward Characteristics

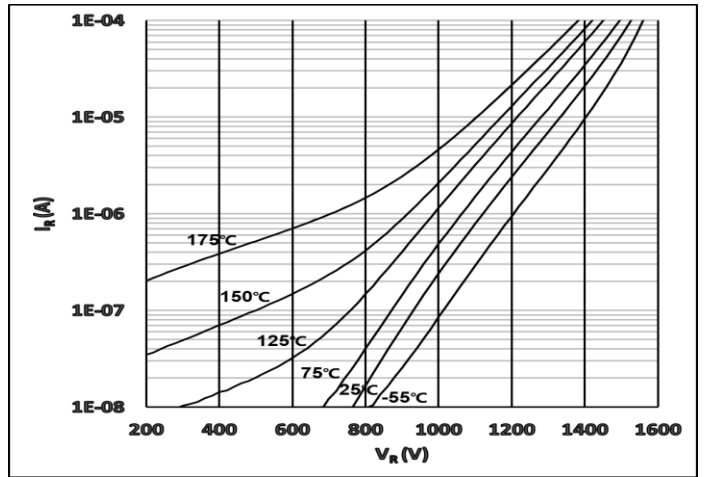
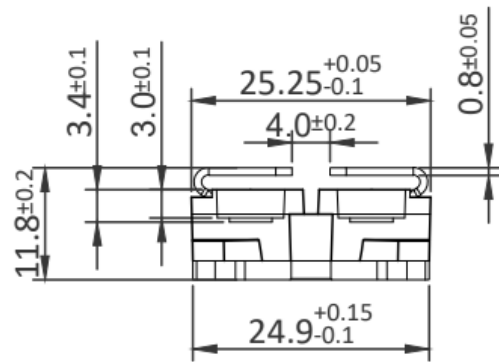
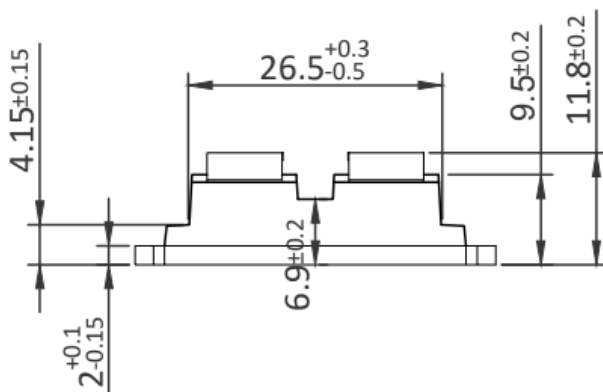
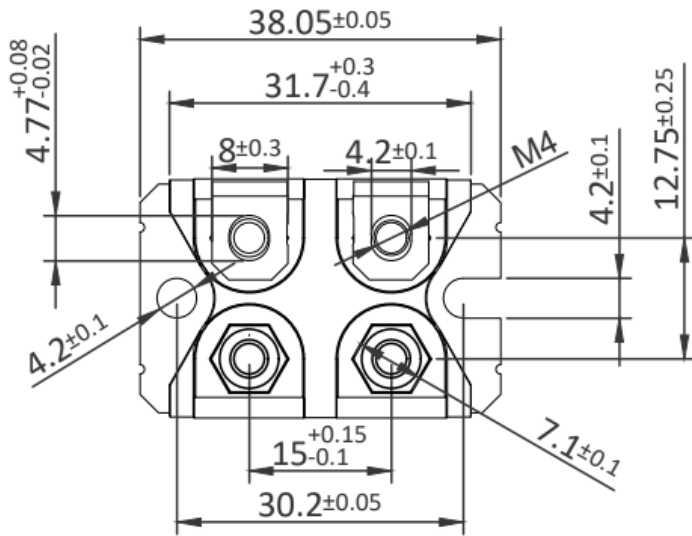


Fig. 26 Typical Reverse Characteristics

Package Dimensions



Notes

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